

CONTENTS

Preface	V
Abstract	VI
Contents	VII
Nomenclature and Abbreviations	X
1 Introduction	1
1.1 Background and applications	1
1.2 Objective and methods	3
2 Physical basics of heat conduction	5
2.1 Heat conduction in solids	5
2.1.1 Non-metallic solids	7
2.1.2 Metallic solids	10
2.1.3 Polymers	11
2.1.4 Effect of porosity	12
2.2 Thermal transfer across interfaces	13
2.3 Thermal contact resistance	14
2.3.1 Solid-solid contact resistance	14
2.3.2 Use of thermal interface materials	17
2.3.3 Solid-liquid contact resistance	19
2.4 Heat conduction in filled polymers	19
2.4.1 A general introduction to effective thermal conductivity of composites	20
2.4.2 Effective thermal conductivity of filled polymers	22
2.4.3 Thermal contact resistance between filled polymers and solids	33
2.5 Advances in development of highly conductive filled polymers	33
2.5.1 Polymers with single-scale filler packing	35
2.5.2 Polymers with hybrid filler packings	36
2.5.3 Polymers with multi-scale filler packings	37
3 Experimental methods and materials	39
3.1 Raw materials and their characteristics	39
3.1.1 Polymers	39
3.1.2 Fillers	41
3.1.3 Substrates	44
3.2 Measuring thermal conductivity with the steady-state cylinder method	48
3.2.1 Introduction to thermal conductivity measurements	48
3.2.2 Measurement principle and apparatus	50
3.2.3 Sample preparation	52
3.2.4 Measurement procedure	54
3.2.5 Evaluation	55
3.2.6 Discussion of measurement uncertainties	57
3.2.7 Extension: evaluation of thermal contact resistances	59

3.3	Measuring thermal contact resistances using micro thermography	60
3.3.1	Introduction to thermal contact resistance measurements	60
3.3.2	Measurement principle and apparatus	61
3.3.3	Sample preparation	62
3.3.4	Calibration procedure	64
3.3.5	Measurement procedure.....	68
3.3.6	Evaluation	68
3.3.7	Discussion of measurement uncertainties.....	72
4	Effective thermal conductivity of single-scale filled polymers.....	76
4.1	Predicting the effective thermal conductivity using microscale simulations	76
4.1.1	Introduction to numerical simulation of heat conduction in filled polymers	77
4.1.2	Microstructure modeling with spherical particles	80
4.1.3	Microstructure modeling with arbitrary particle morphologies.....	87
4.1.4	Computation of microscale heat conduction	92
4.1.5	Evaluations	96
4.2	Effect of the fillers maximum packing density	102
4.2.1	Microscale packing structure.....	102
4.2.2	Width of the particle size distribution	104
4.2.3	Particle morphology.....	106
4.2.4	An experimental approach for determining the maximum packing density.....	112
4.3	Effects of the spatial filler particle arrangement.....	115
4.3.1	Inhomogeneous particle distribution	115
4.3.2	Agglomerated filler packings	117
4.3.3	Sedimented filler packings	120
4.4	Effects of the thermal filler and polymer properties	123
4.4.1	Filler thermal conductivity	124
4.4.2	Polymer thermal conductivity.....	125
4.4.3	Thermal interfacial resistances between filler particles and polymers.....	127
4.5	Experimental validation of microscale simulations	129
4.6	Chapter summary and conclusion	134
5	Effective thermal conductivity of multi-scale filled polymers.....	139
5.1	Predicting the effective thermal conductivity using a multi-step approach.....	139
5.1.1	Necessity for a multi-step approach	139
5.1.2	The general homogenization scheme.....	142
5.1.3	Considering interfacial transition zones (ITZ)	146
5.2	Experimental validation and formulation studies	154
5.3	Effect of the fillers' maximum packing densities	159
5.4	Effect of the fillers' thermal conductivities	162
5.5	Chapter summary and conclusion	165
6	Thermal transfer from filled polymers to solid substrates.....	166
6.1	Assessing the phenomenon with microscale simulations	166
6.1.1	Microstructure modeling	166
6.1.2	Computation of microscale heat conduction	171
6.1.3	Evaluations	173

6.2	Introductory investigations with unfilled polymers	176
6.3	Definition of thermal and geometrical boundary layer	180
6.4	Effects of the microscale packing and substrate structure.....	186
6.4.1	Particle size, particle size distribution, and filler volume fraction.....	186
6.4.2	Boundary layer packing structure	195
6.4.3	Roughness characteristics of the substrate.....	200
6.4.4	Local variations.....	209
6.5	Effects of the components thermal conductivities.....	211
6.6	Thin layer phenomena	214
6.7	Chapter summary and conclusion	215
7	Summary and conclusion	217
	Outlook	220
	References	XIII
	Published work of the author	XIII
	General references.....	XIII
	List of Figures	XXXIII
	List of Tables.....	XXXVIII
Appendix A	Supplementary models to chapter 1	XXXIX
A.1	Cooper-Mikic-Yovanovich model for solid contribution to contact conductance ...	XXXIX
A.2	Gap conductance model for two conforming rough surfaces.....	XXXIX
A.3	Fractal model for predicting thermal contact resistance at solid-liquid interfaces.....	XL
Appendix B	Details on evaluations and uncertainty analysis in chapter 3	XLII
B.1	Regression parameters for steady-state cylinder method	XLII
B.2	Uncertainty estimation for the steady-state cylinder method	XLII
B.3	Uncertainty estimation for micro thermography	XLIV
Appendix C	Supplementary details on modeling and simulation	XLVII
C.1	Details on RVE size determination.....	XLVII
C.2	Computational details for steady-state heat conduction through RVEs	XLIX
C.3	Derivation of the first ϕ correction for the ITZ extension model	XLIX
C.4	Derivation of the second ϕ correction for the ITZ extension model	LI
Appendix D	Supplementary results of simulative studies in chapter 6	LIII
D.1	Heat transfer between unfilled polymers and rough substrate surfaces	LIII
D.2	Comparison of micro thermography and FPS transition simulation	LVI
D.3	Tabular results of the simulative studies in chapter 6.4.....	LVII
D.4	Tabular results of the simulative studies in chapter 6.5.....	LIX